

Session wise - Course Plan

Department of Electronics and Communication Engineering

SEMESTER :I NAME OF THE FACULTY : Mr. Mahesh S Gour

BRANCH : ECE DATE OF COMMENCEMENT : 26.09.2016 SUBJECT : AESD DATE OF CLOSING : 20.12.2016

SUBJECT CODE : 16EVE13 CLASS STRENGTH : 7 NO OF HRS/WK : 4 TOTAL HRS : 50

S.No	Chapter no (No of hrs planed for the chapter)	DATE	Topics planned for the session	Teaching Aids	Assignment s/ Tests planned for the chapter	Topics covered As per plan
1	1/1	26/9/16	module –1 Embedded System: Embedded vs General computing system, classification, application and purpose of ES. Core of an Embedded System, Memory, Sensors	Board, chalk, Duster	Prerequisite	
3	3/1	26/9/16	Actuators, LED, Opto coupler, Communication Interface Reset circuits, RTC, WDT,	"		
4	4/1	28/9/16	Characteristics and Quality Attributes of	,,	Assignment - I	

		Embedded Systems			
		Approaches			
5/1	29/9/16	Characteristics and Quality	,,		
		Attributes of			
		Embedded Systems (contd)			
6/1	30/9/16	- Characteristics and Quality	,,		
		Attributes of			
		Embedded Systems(contd)			
1/2	1/10/16	module –2			
		Hardware Software Co-Design,			
		embedded firmware design			
		approaches, computational			
		models			
2/2	3/10/16	embedded firmware	,,		
		development languages,			
3/2	4/10/16	Integration and testing of	Board,		
		Embedded Hardware and			
		firmware			
4/2	5/10/16	Components in	,,	Assignment	
		embedded system development		-11	
		environment (IDE),			
5/2	6/10/16	files	**		
		generated during compilation			
6/2	11/10/16	simulators, emulators and	,,		
		deougging			
1/3	12/10/16	Module –3	,,		
		ARM-32 bit Microcontroller:			
		Thumb-2 technology			
2/3	15/10/16	applications of ARM,			
		Architecture of ARM Cortex			
		M3			
3/3	15/10/16	Various Units in the	,,		
		architecture,			
	6/1 1/2 2/2 3/2 4/2 5/2 6/2 1/3	6/1 30/9/16 1/2 1/10/16 2/2 3/10/16 3/2 4/10/16 4/2 5/10/16 5/2 6/10/16 1/3 12/10/16 2/3 15/10/16	Approaches 5/1 29/9/16 Characteristics and Quality Attributes of Embedded Systems (contd) 6/1 30/9/16 - Characteristics and Quality Attributes of Embedded Systems(contd) //2 1/10/16 module -2 Hardware Software Co-Design, embedded firmware design approaches, computational models 2/2 3/10/16 Embedded firmware development languages, 1/2 4/10/16 Integration and testing of Embedded Hardware and firmware 4/2 5/10/16 Components in embedded system development environment (IDE), 5/2 6/10/16 files generated during compilation simulators, emulators and debugging 1/3 12/10/16 Module -3 ARM-32 bit Microcontroller: Thumb-2 technology applications of ARM, Architecture of ARM Cortex M3 15/10/16 Various Units in the	Approaches	Approaches S/1 29/9/16 Characteristics and Quality Attributes of Embedded Systems (contd)

17	4/3	19/10/16	Various Units in the	Board,		
			architecture(contd)	chalk, Duster		
18	5/3	20/10/16	General Purpose	,,	Assignment	
			Registers, Special Registers		-III	
19	6/3	2/11/16	General Purpose	,,		
			Registers, Special			
20	7/3	3/11/16	Registers(cond) exceptions, interrupts, stack			
20	113	3/11/10	operation, reset sequence	"		
21	1/4	5/11/16	MODULE -4	,,		
			Instruction Sets : Assembly basics, Instruction list			
22	2/4	6/11/16	Assembly basics, Instruction list(contd)	,,		
23	3/4	10/11/16	description, useful instructions			
24	4/4	12/11/16	Memory Systems, Memory	,,	Assignmnt –IV	
27		1.7/1.1/1.6	maps		-1 V	
25	5/4	15/11/16	Memory Systems, Memory maps (contd)	,,		
26	6/4	17/11/16	Cortex M3 implementation overview	,,		
27	7/4	19/11/16	pipeline and bus interface	,,		
28	8/4	25/11/16	pipeline and	Board,		
			bus interface (contd)	chalk,		
29	1/5	27/11/16	Module –5	Duster ,,	Assignment	
			Exceptions	,,	-V	
30	2/5	2/12/16	Nested Vector interrupt	,,		
			controller design,			
31	3/5	5/12/16	Systick Timer			
32	4/5	8/12/16	Cortex-M3 Programming using assembly			
33	5/5	9/12/16	Cortex-M3 Programming using assembly and			
34	6/5	10/12/16	C language CMSIS			_
J T	0/3	10/12/10	CIVIDIO	,,		



Session wise - Course Plan

Department of Electronics and Communication Engineering

SEMESTER :I NAME OF THE FACULTY : Mr. Sharana Basava

BRANCH : ECE DATE OF COMMENCEMENT : 26.09.2016
SUBJECT : DSDV DATE OF CLOSING : 20.12.2016
SUBJECT CODE : 16EVE151 CLASS STRENGTH : 2
NO OF HRS/WK : 4 TOTAL HRS : 50

S.No	Chapter no (No of hrs planed for the chapter)	DATE	Topics planned for the session	Teaching Aids	Assignment s/ Tests planned for the chapter	Topics covere d As per plan
1	1/1	26/9/16 27/9/16 28/9/16 29/9/16 30/9/16	module –1 Introduction and methodology, digital s/ms and embedded s/ms, binary representation and circuit elements, real world circuits,models,design methodology.	Board, chalk, Duster	Prerequisite	
2	2/1	1/10/16 3/10/16 4/10/16 5/10/16 6/10/16 11/10/16	Module 2 Number basics Unsigned and signed integers,fixed and floating point numbers Sequential basics Storage elements,counters,sequential data paths and control,clocked	,,		

			synchronous timing			
			methodology			
3	3/1	12/10/16	Module 3	,,		
		15/10/16	Memories:	,,,		
		15/10/16	Concepts ,memory types,error			
		15/10/16	detection and correction			
		19/10/16	Implementation fabrics			
		20/10/16	ICs,PLDs,packaging and			
		20/10/10	circuit boards,interconnection			
		2/11/16	and signal integrity			
		3/11/16				
4	4/1	5/11/16	Module4	,,	Assignment - I	
		6/11/16	Processor basics:		_	
		11/11/16	Embedded computer			
			organization,instruction and			
		12/11/16	data,interfacing with memory			
		15/11/16	I/O interfacing:			
		17/11/16	I/O devices,I/O			
		10/11/16	controllers, parallel buses, serial			
		19/11/16	transmission,I/O software.			
		25/11/16				
	F/1	05/11/16	M 115			
5	5/1	25/11/16	Module5	,,		
		2/12/16	Accelerators:concepts,case			
		5/12/16	study, verification of accelerators.			
		8/12/16	Design methodology:			
			Design flow,design			
		9/12/16	optimization,design for test			
		10/12/16	1			
6	6/1	30/9/16		,,		
	-3-			77		

7	1/2	1/10/16	module –2		
8	2/2	3/10/16		,,	
9	3/2	4/10/16		Board, chalk, Duster	
10	4/2	5/10/16		,,	Assignment -II
11	5/2	6/10/16		"	
12	6/2	11/10/16		,,	
13	1/3	12/10/16	Module –3	,,	
15	2/3	15/10/16			
16	3/3	15/10/16		,,	
17	4/3	19/10/16		Board, chalk, Duster	
18	5/3	20/10/16		,,	Assignment –III
19	6/3	2/11/16		,,	
20	7/3	3/11/16		,,	
21	1/4	5/11/16	MODULE -4	,,	
22	2/4	6/11/16		,,	
23	3/4	10/11/16			
24	4/4	12/11/16		,,	Assignmnt -IV
25	5/4	15/11/16		,,	
26	6/4	17/11/16		,,	
27	7/4	19/11/16		,,	
28	8/4	25/11/16		Board, chalk, Duster	

29	1/5	27/11/16	Module –5	"	Assignment -V	
30	2/5	2/12/16		"		
31	3/5	5/12/16				
32	4/5	8/12/16				
33	5/5	9/12/16				
34	6/5	10/12/16		,,		

Signature of faculty

Signature of HOD

Signature of Principal



Session wise – Course Plan

Department of Electronics and Communication Engineering

SEMESTER :I NAME OF THE FACULTY : Dr. Ramesh
BRANCH : ECE DATE OF COMMENCEMENT : 26.09.2016
SUBJECT : DVD DATE OF CLOSING : 20.12.2016
SUBJECT CODE : 16EVE12

SUBJECT CODE : 16EVE12 CLASS STRENGTH : 7 NO OF HRS/WK : 4 TOTAL HRS : 50

S.No	Chapter no (No of hrs planed for the chapter)	DATE	Topics planned for the session	Teaching Aids	Assignment s/ Tests planned for the chapter	Topics covere d As per plan
1	1/1	26/9/16	module –1 MOS Transistor: The Metal Oxide Semiconductor (MOS) Structure,	Board, chalk, Duster	Prerequisite	
2	2/1	26/9/16	The MOS System under External Bias,	,,		
3	3/1	27/9/16	Structure and Operation of MOS Transistor	,,		
4	4/1	28/9/16	Structure and Operation of MOS Transistor (contd)	,,	Assignment - I	
5	5/1	29/9/16	MOSFET Current-Voltage Characteristics,	"		
6	6/1	30/9/16	MOSFET Scaling and Small-Geometry Effects.	,,		
7	7/1	1/10/16	MOS Inverters-Static Characteristics: Introduction, Resistive-Load inverter			
8	8/1	3/10/16	Inverters with n_Type MOSFET Load.	"		

9	1/2	4/10/16	module –2	Board,		
			MOS Inverters-Static	chalk,		
			Characteristics: CMOS	Duster		
			Inverter.			
10	2/2	5/10/16	MOS Inverters: Switching Characteristics and Interconnect Effects: Introduction, Delay-Time Definition,	"	Assignment -II	
11	3/2	6/10/16	Calculation of Delay Times, Inverter Design with Delay Constraints,	,,		
12	4/2	11/10/16	Esimation of Interconnect Parasitics, Calculation of Interconnect Delay	"		
13	5/3	12/10/16	Switching Power Dissipation of CMOS	,,		
			Inverters.			
15	1/3	15/10/16	Module –3			
			Semiconductor Memories:			
			Introduction			
16	2/3	15/10/16	Dynamic Random Access Memory	,,		
			(DRAM)			
17	3/3	19/10/16	Dynamic Random Access Memory (DRAM) (contd)	Board, chalk, Duster		
18	4/3	20/10/16	Static Random Access Memory (SRAM),	,,	Assignment -III	
19	5/3	2/11/16	Nonvolatile Memory	,,		
20	6/3	3/11/16	Flash Memory, Ferroelectric Random Access Memory (FRAM).	,,		
21	1/4	5/11/16	MODULE -4	,,		
			Dynamic Logic Circuits: Introduction, Basic Principles of Pass Transistor Circuits,			
22	2/4	6/11/16	Voltage Bootstrapping,	,,		

			Synchronous Dynamic Circuit Techniques			
23	3/4	10/11/16	Dynamic CMOS Circuit Techniques, High Performance Dynamic CMOS Circuits.			
24	4/4	12/11/16	BiCMOS Logic Circuits: Introduction	,,	Assignmnt -IV	
25	5/4	15/11/16	Bipolar Junction Transistor (BJT): Structure and Operation	,,		
26	6/4	17/11/16	Dynamic Behavior of BJTs, Basic BiCMOS Circuits	,,		
27	7/4	19/11/16	Static Behavior, Switching Delay in BiCMOS Logic Circuits, BiCMOS Applications.	,,		
28	8/4	25/11/16	Static Behavior, Switching Delay in BiCMOS Logic Circuits, BiCMOS Applications. (contd)	Board, chalk, Duster		
29	1/5	27/11/16	Module –5 Chip Input and Output (I/O) Circuits: Introduction, ESD Protection, Input Circuits	,,	Assignment -V	
30	2/5	2/12/16	Output Circuits and L(di/dt) Noise, On-Chip Clock Generation and Distribution	,,		
31	3/5	5/12/16	Latch-Up and Its Prevention			
32	4/5	8/12/16	Design for Manufacturability: Introduction, Process Variations,			
33	5/5	9/12/16	Basic Concepts and Definitions,			
34	6/5	10/12/16	Design of Experiments and Performance Modeling.	,,		



Session wise – Course Plan

Department of Electronics and Communication

SEMESTER: INAME OF THE FACULTY: Rajesh GopalBRANCH: TCEDATE OF COMMENCEMENT: 15.10/2016SUBJECT: ADMDATE OF CLOSING: 15.12/.2016

SUBJECT CODE: 16ELD11 CLASS STRENGTH: 08
NO OF HRS/WK: 5 TOTAL HRS: 52

Sess ion No	Chapter no (No of hrs planed for the module)	DATE	Topics planned for the session	Teaching Aids	Assign ments/ Tests planned for the chapter	Topics covere d As per plan
1	1/(10 hrs)	15/10/16 To 30/10/16	Module 1: Linear Algebra-I, Vector spaces, sub-space, linearly independent vectors, basis vectors, dimension of vector space, linear transformation, rank-nullity theorem, matrix form of linear transformation	Board, chalk, duster		
2	2/(10 hrs)	1/11/16 To 15/11/16	Module2: Probability Theory Review of basic theory, definition of random variables, probability distribution, probability mass and density function, expectation, moments, central moments, characteristic functions, probability generating and moment generating functions, Binomial, Poisson, Exponential, Gaussian and Rayleigh distribution	,,		
3	3/(10 hrs)	16/11/16 To 27/11/16	Module 3-Joint Probability distributions, Properties of CDF, PDF, PMF, conditional distributions, Expectation, covariance and correlation, Independent random variables, Central limit theorem, Random process, Stationary and Ergodic, Auto correlation function, properties, Gaussiam random process			
4	4 /(10 hrs)	28/11/16 To	Module 4: Linear Algebra II, Eigen values and Eigenvectors	"		

		7/12/16	of real symmetric matrices, Given's method, orthogonal vectors and bases, Gram- Schmidt orthogonalization, QR decomposition, Singular value decomposition, least square approximations.		
5	5/(10 hrs)	8/12/16 To 15/12/16	Module 5: Calculus of variations, Concept of functional- Eulers equation, functional dependent on first and higher order derivatives, functional on several dependent variables. Isoperimetric problems-variation problems with moving boundaries	,,	

Signature of faculty

Signature of HOD

Signature of Principal



Session wise – Course Plan

Department of Electronics and Communication Engineering

SEMESTER :I NAME OF THE FACULTY : Mr. Sharanabasappa S H

BRANCH : ECE DATE OF COMMENCEMENT : 26.09.2016 SUBJECT : LPVLSI DATE OF CLOSING : 20.12.2016

SUBJECT CODE : 16EVE14 CLASS STRENGTH : 2 NO OF HRS/WK : 4 TOTAL HRS : 50

S.No	Chapter no (No of hrs planed for the chapter)	DATE	Topics planned for the session	Teaching Aids	Assignment s/ Tests planned for the chapter	Topics covere d As per plan
1	1/1	26/9/16	module -1 Introduction: Need for low power VLSI chips, Charging and discharging capacitance.	Board, chalk, Duster	Prerequisite	
2	2/1	26/9/16	Short circuit current in CMOS leakage current, Static current	,,		
3	3/1	27/9/16	Basic principle of low power design	"		
4	4/1	28/9/16	Low power figure of merits	,,	Assignment - I	
5	5/1	29/9/16	Simulation Power analysis: SPICE circuit simulators, Discrete transistor modelling and analysis.	,,		
6	6/1	30/9/16	Gate level logic simulation Architecture level analysis, Data correlation analysis in DSP systems, Monte Carlo simulation	,,		
7	1/2	1/10/16	module –2			

			Probabilistic power analysis:			
			Random logic signals			
8	2/2	3/10/16	Probability & frequency Probabilistic power analysis techniques,	,,		
9	3/2	4/10/16	Signal entropy	Board,		
	3/2	1710/10	Signal chiropy	chalk, Duster		
10	4/2	5/10/16	Circuit:transistor and gate	,,	Assignment	
			sizing ,equivalent pin ordering,		-II	
11	5/2	6/10/16	Network restructuring and	,,		
			reorganizing, special latches			
			and flip_flops			
12	6/2	11/10/16	Low power digital cell library, adjustable device threshold voltage	,,		
13	1/3	12/10/16	Module –3	,,		
			Logic level: Gate			
			reorganization, Signal gating,			
			logic encoding			
15	2/3	15/10/16	State machine encoding Pre-computation logic			
16	3/3	15/10/16	Low power clock	,,		
			distribution: Power			
			dissipation in clock			
			distribution			
17	4/3	19/10/16	Single driver vs distributed	Board,		
			buffers	chalk, Duster		
18	5/3	20/10/16	Zero skew vs tolerable skew	,,	Assignment –III	
19	6/3	2/11/16	Chip package and package codesign of clock level	,,		
21	1/	E /1 1 /1 <	MODULE 4	,,		
21	1/4	5/11/16	MODULE -4	,,		

			Low power Architecture & Systems: Power & performance management,			
22	2/4	6/11/16	Power and performance management, Switching activity reduction	,,		
23	3/4	10/11/16	Parallel architecture with voltage reduction Flow graph transformation,			
24	4/4	12/11/16	Low power arithmetic components	,,	Assignmnt -IV	
25	5/4	15/11/16	Introduction	,,		
26	6/4	17/11/16	Circuit design style	,,		
27	7/4	19/11/16	Adders ,multipliers	,,		
28	8/4	25/11/16	division	Board, chalk, Duster		
29	1/5	27/11/16	Module –5 Low power memory design. Introduction , source and reduction of power dissipation in memory subsystem	,,	Assignment -V	
30	2/5	2/12/16	Sources and power dessipation in DRAM and SRAM	,,		
31	3/5	5/12/16	S			
32	4/5	8/12/16	Algorithmic level analysis & optimization, Architectural level estimation & synthesis			
33	5/5	9/12/16	Advanced technique: adiabatic computation.			
34	6/5	10/12/16	Pass transistors, asyncronous circuits.	,,		